

Filename: PMP8711RevA - BoM.xls

Date: 10/21/2013

## PMP8711RevA - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	100uF	Capacitor, Aluminum, 50V, ±20%	0.328 x 0.328 inch	EEEFK1H101P	Panasonic
1	C3	3.3uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	Std	Std
1	C4	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	Std	Std
1	C6	33nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
1	C7	2.2nF	Capacitor, Ceramic, 50V, X7R, 15%	603	Std	Std
1	C8	3.3nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
1	C9	1uF	Capacitor, Ceramic, 16V, X7R, 15%	805	Std	Std
1	C11	1uF	Capacitor, Ceramic, 50V, X7R, 10%	1206	Std	Std
1	C101	6800uF	Capacitor, Aluminum, 50V		KMQ Series	Nippon Chemi-Con
1	D1	MBRS260	Diode, Schottky, xx-A, xx-V	SMB	STD	STD
2	GND_IN GND_OUT	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	L1	27uH	Inductor, SMT, 51mOhm, 2.9A rms, 3.5A sat	12 x 12 mm	744771127	Wuerth
1	Q1	SI4850EY	MOSFET, Nch, 60V, 8.5A, 22milliohm	SO8	SI4850EY	Vishay
1	R1	732k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R2	20.0k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R3	47.5k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R4	100	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R5	50m	Resistor, Chip, 1/4 watt, 1%	1206	Std	Std
1	R6	61.9k	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R7-8	121k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R101	51.1	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	U1	LM3481	IC, High Efficiency Low-Side N-Channel Controller	MSOP	LM3481MM	Texas Instruments
2	VIN VOUT	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone

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